Title: Detechant for	20160920002	A	PCN Date:		Sept.	26, 2016	
Title: Datasheet for	ULN2003B						
Customer Contact:	PCN Manager			Dep	ot:	Quality Services	
Change Type:							
Assembly Site		Design			Wafer	Bump Site	
Assembly Process		Data Sheet			Wafer	Bump Material	
Assembly Materials		Part number	change			Bump Process	
Mechanical Specific		Test Site		Ц		Fab Site	
Packing/Shipping/L	abeling	Test Process				Fab Materials	
					Wafer	Fab Process	
	<u> </u>	tification D	etails				
Description of Change: The previous version of th SN74HCT245 device datas 20160920002 pertains to Texas Instruments Incorpo	heet. Revision the ULN2003B	A is being issu datasheet rev	ied to replace ision.	the	previo	us notification. PC	
he product datasheet(s) i he following change histo			zed below.				
Texas Instruments	, p			2 11 161	= 2014 DE\	ULN2003B /ISED AUGUST 2016	
 Deleted Hammer Drivers from Updated <i>Pin Functions</i> table 						3	
Deleted Package Themal Infor		-					
Moved Storage temperature, T							
	Deleted V ₁ from Recommended Operating Conditions						
Moved Operating free-air temperature, T _A to Recommended Operating Conditions							
Deleted Output Current vs Input Current graph from Typical Characteristics section							
 Added her vs lour to Typical C 						•	
 Added h_{FE} vs I_{OUT} to Typical Ci Deleted Thermal Information g Figure 6 through Figure 14 							
Deleted Thermal Information g						6	
Deleted Thermal Information g Figure 6 through Figure 14	f Documentation Up	dates section and C			tion	6 14	
 Deleted Thermal Information g Figure 6 through Figure 14 Added Receiving Notification of The datasheet number will Device Family 	f Documentation Up	dates section and C			tion	6 	
 Deleted <i>Thermal Information</i> g Figure 6 through Figure 14 Added <i>Receiving Notification</i> of 	f Documentation Up	dates section and C			tion	6 14	
Deleted Thermal Information g Figure 6 through Figure 14 Added Receiving Notification of The datasheet number will Device Family ULN2003B These changes may be rev	f Documentation Up be changing.	dates section and C Change From: SLRS064A	ommunity Resource		tion	6 	
 Deleted Thermal Information g Figure 6 through Figure 14 Added Receiving Notification of The datasheet number will Device Family ULN2003B These changes may be reventtp://www.ti.com/production 	f Documentation Up be changing.	dates section and C Change From: SLRS064A	ommunity Resource		tion	6 	
 Deleted Thermal Information g Figure 6 through Figure 14 Added Receiving Notification of The datasheet number will Device Family 	f Documentation Up be changing.	dates section and C Change From: SLRS064A atasheet links	ommunity Resource		tion	6 	

the actual device.

 Changes to product identification resulting from this PCN:

 None.
 Product Affected:

 ULN2003BDR
 ULN2003BN

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com